

Gold Bonding Wire (Au100) Gold 25um (1.0mil)**Product Highlights**

High Purity Gold > 99.99% (4N). Designed specifically for wire bonding. Gold bonding wire is used to connect electrical components in many industries, including electronics, aerospace and medicine. Gold bonding wire has excellent electrical conductivity, stability and resistance to corrosion. It is an important material in semiconductor and electronic device manufacturing. It is commonly used for wire bonding to electrically connect microchip semiconductor dies to the terminals of a chip package or directly to a substrate. Commonly used by integrated circuit (IC) packaging shops, research labs and advanced manufacturing facilities.

**Specifications**

Alloy:	Au100
Melting Point:	1,064°C (1,947°F)
Packaging:	Spool
Diameter:	25µm (1.0 mil)
Length:	100m (328 feet)
Shelf Life:	> 12 months
Purity:	4N (>99.99%)
Wire Weight:	950 mg

Storage and Handling

Store in a dry non-corrosive environment.

Transportation

This product has no shipping restrictions.

Test Results

Test J-STD-004 or other requirements as stated	Test Requirement	Result
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Compliant

Conforms to the following Industry Standards:

J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):

Yes

RoHS 3 Directive (EU) 2015/863:

Yes

Chip Quik Gold Bonding Wire (Au100) Orderable Part Numbers

Part Number	Gold (Au) Purity	Diameter	Length	Photo
CQB-AU100-20um	4N (>99.99%)	20µm (0.8 mil)	100m (328 feet)	
CQB-AU100-23um	4N (>99.99%)	23µm (0.9 mil)	100m (328 feet)	
CQB-AU100-25um	4N (>99.99%)	25µm (1.0 mil)	100m (328 feet)	